

30V N-Channel Enhancement Mode MOSFET

Voltage

30 V

Current

120 A

Features

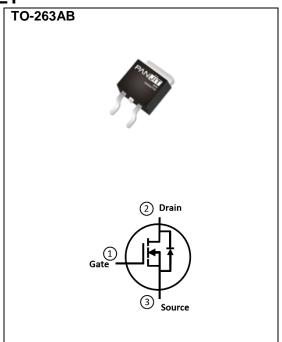
- RDS(ON), VGS@10V, ID@90A<1.8m Ω
- RDS(ON), VGS@4.5V, ID@50A<2.4m Ω
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: TO-263AB Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 1.6924 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V_{DS}	30	V	
Gate-Source Voltage		V_{GS}	±20		
Continuous Drain Current(Note 3)	T _C =25°C	ID	120		
	T _C =100°C		120	Α	
Pulsed Drain Current(Note 1)	T _C =25°C	I _{DM}	480		
Power Dissipation	T _C =25°C	D.	250	W	
	T _C =100°C	Pb	125		
Continuous Drain Current(Note 4)	T _A =25°C	l _D	35	А	
	T _A =70°C		29.3		
Power Dissipation	T _A =25°C	Po	3.8	W	
	T _A =70°C		2.6		
Single Pulse Avalanche Current ^(Note 5)		I _{AS}	26.3	Α	
Single Pulse Avalanche Energy ^(Note 5)		Eas	354	mJ	
Operating Junction and Storage Temperature Range		T_{J}, T_{STG}	-55~175	°C	
Thermal Resistance ^(Note 4)	Junction to Case	$R_{\theta JC}$	0.6	°C/W	
	Junction to Ambient	$R_{\theta JA}$	40		



Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	30	-	-	V	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.2	1.6	2.5		
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =90A	ı	1.42	1.8	mΩ	
		V _{GS} =4.5V, I _D =50A	i	1.82	2.4		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	1	uA	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA	
Dynamic ^(Note 6)							
Total Gate Charge	Q_g		-	65	90		
Gate-Source Charge	Q _{gs}	V _{DS} =24V, I _D =90A, V _{GS} =10V	-	8.7	-	nC	
Gate-Drain Charge	Q_{gd}	VGS=1UV	i	11	-		
Input Capacitance	Ciss	\/ OF\/ \/ O\/	i	4737	6200	pF	
Output Capacitance	Coss	V _{DS} =25V, V _{GS} =0V,	-	2131	2800		
Reverse Transfer Capacitance	Crss	f=1MHz	-	78	140		
Gate resistance	Rg	f=1MHz	-	1.5	-	Ω	
Turn-On Delay Time	td _(on)	\\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-	13.7	-		
Turn-On Rise Time	tr	V _{DS} =24V, I _D =90A,	-	10	-		
Turn-Off Delay Time	td _(off)	$V_{GS}=10V, R_{G}=3\Omega$ (Note 2)	-	43	-	ns	
Turn-Off Fall Time	tf	(Note 2)	-	17	-		
Drain-Source Diode							
Diode Forward Current	Is	Tc=25°C	-	-	120	_	
Pulsed Diode Forward Current	I _{SM}	1c=25 C	ı	-	480	A	
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V	i	0.8	1.3	V	
Reverse Recovery Time	Trr	V _{DD} =24V,V _{GS} =0V,	-	55	-	ns	
Reverse Recovery Charge	Qrr	Is=20A,dIs/dt=100A/us	-	56	-	nC	

NOTES:

- 1. Pulse width < 300us, Duty cycle < 2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an R_{BJC}=0.6°C/W, Package limited 120A.
- 4. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 5. E_{AS} is calculated based on the condition of L=1mH, I_{AS}=26.6A, V_{DD}=30V, V_{GS}=10V. 100% test at L=0.5mH, I_{AS}=26.3A in production.
- 6. Guaranteed by design, not subject to production testing.



TYPICAL CHARACTERISTIC CURVES

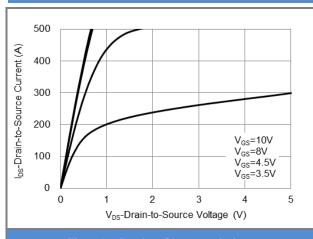
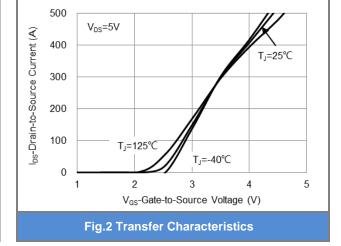


Fig.1 On-Region Characteristics



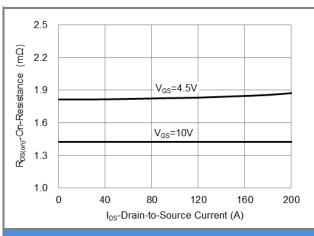


Fig.3 On-Resistance vs. Drain Current

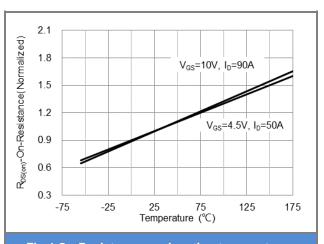
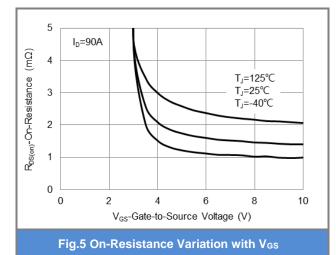


Fig.4 On-Resistance vs. Junction temperature



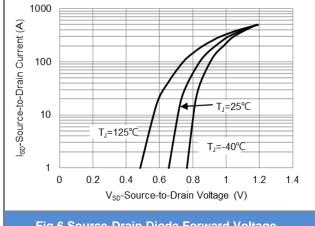


Fig.6 Source-Drain Diode Forward Voltage



TYPICAL CHARACTERISTIC CURVES

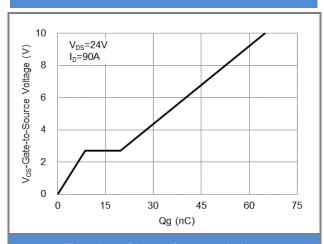


Fig.7 Gate-Charge Characteristics

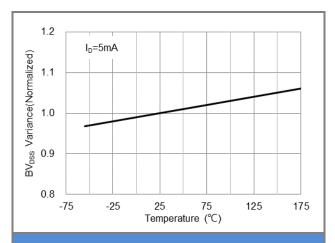


Fig.8 Breakdown Voltage Variation vs. Temperature

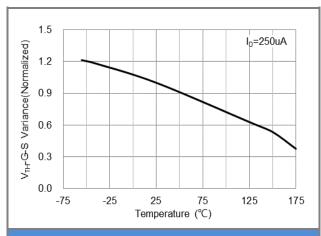


Fig.9 Threshold Voltage Variation with Temperature

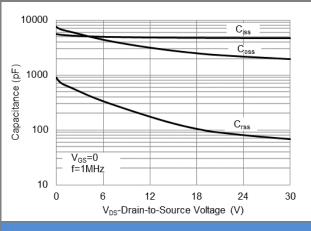
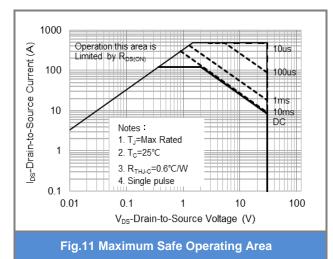


Fig.10 Capacitance vs. Drain-Source Voltage



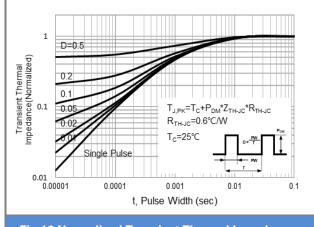


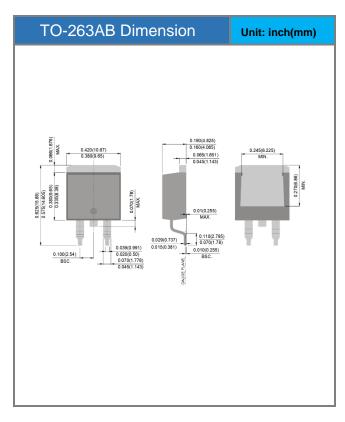
Fig.12 Normalized Transient Thermal Impedance

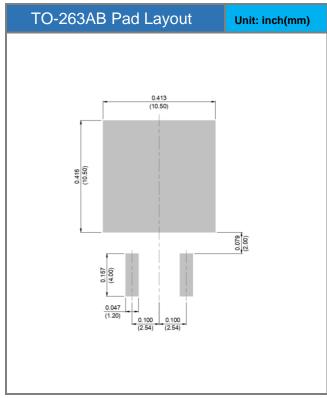


Product and Packing Information

Part No.	Package Type	Packing Type	Marking	
PJB120N03S-AU	TO-263AB	800 pcs / 13" reel	120N03S	

Packaging Information & Mounting Pad Layout







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